



SDM1U20CSP

1.0A SCHOTTKY BARRIER RECTIFER CHIP SCALE PACKAGE

Product Summary

V _{RRM} (V)	I _O (A)	V _F Max (V)	I _R Max (μΑ)
20	1.0	0.44	100

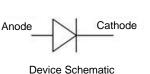
Features and Benefits

- Low forward voltage (V_F) minimizes conduction losses and improves efficiency.
- Reduced high-temperature reverse leakage. Increased reliability against thermal runaway failure in high temperature operation.
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

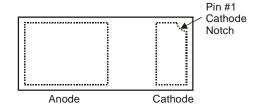
The SDM1U20CSP is a 20V, 1A Schottky barrier rectifier that is optimized for low, forward-voltage drop and low leakage current. Housed in a compact chip scale package (CSP), the SDM1U20CSP occupies only 0.84 mm² board-space with low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency while at the same time reducing board space. It is ideally suited for use in portable applications as:

- **Blocking Diodes**
- **Boost Diodes**
- Switching Diodes
- Reverse Protection Diodes



Mechanical Data

- Case: X3-WLB1406-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
SDM1U20CSP-7	X3-WLB1406-2	5,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

X3-WLB1406-2

Pin 1 X8

X8=Product Type Marking Code YM=Date Code Marking Y=Year (ex: C=2015) M=Month (ex: 11=November) Dot Denotes Cathode Pin

January 2016

Date Code Key

Year	201	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D		E	F		G		H
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	V
Average Rectified Output Current	lo	1.0	А
Repetitive Peak Forward Current (Pulse Wave = 1 Sec, Duty Cycle = 66%)	I _{FRM}	5.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	18	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{ heta JA}$	140	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{ heta JA}$	73	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

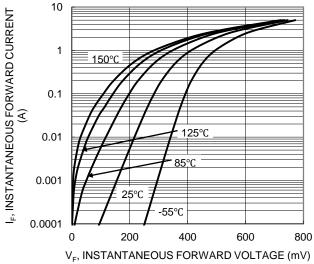
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

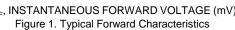
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Dren	M	_	_	0.39	mV	I _F = 0.5A
Forward Voltage Drop	VF	_	_	0.44		I _F = 1.0A
Reverse Current (Note 7)	I _R	_	_	25	μΑ	V _R = 10V
			-	100		V _R = 20V
Junction Capacitance	CJ	I	76	1	pF	$V_R = 4V$, $f = 1.0MHz$

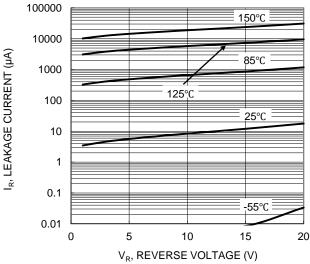
Notes:

- Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
 Device mounted on FR-4 PCB, 2oz. 1 square inch Copper.
 Short duration pulse test used to minimize self-heating effect.









 $V_{\rm R}$, REVERSE VOLTAGE (V) Figure 2. Typical Reverse Characteristics

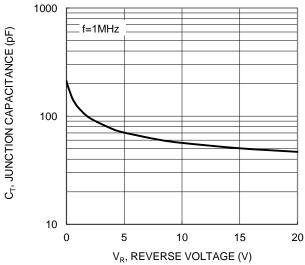


Figure 3. Typical Junction Capacitance

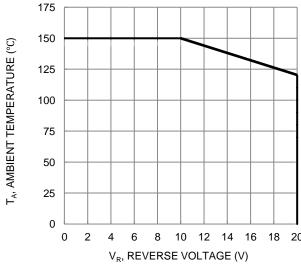


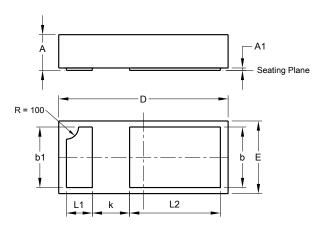
Figure 4. Operating Temperature Derating



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

X3-WLB1406-2

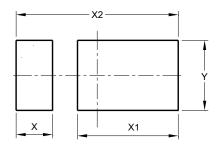


X3-WLB1406-2						
Dim	Min	Max	Тур			
Α	0.250	0.300	0.275			
A1	0.000	0.015	-			
b	0.45	0.55	-			
b1	0.45	0.55	-			
D	1.37	1.43	1.40			
Е	0.57	0.63	0.60			
k	-	-	0.30			
L1	0.20	0.26	-			
L2	0.70	0.80	-			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

X3-WLB1406-2



Dimensions	Value		
Dilliensions	(in mm)		
Х	0.304		
X1	0.840		
X2	1.352		
Υ	0.580		



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